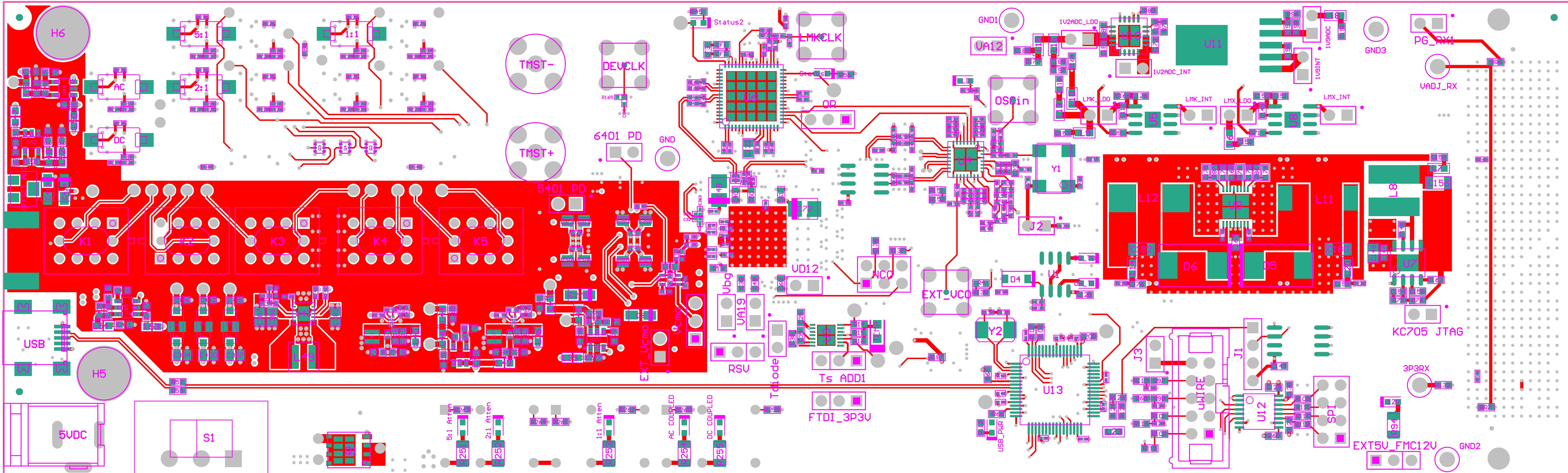


Top Layer L1



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: [No Variations]

VIEWED FROM TOP SIDE

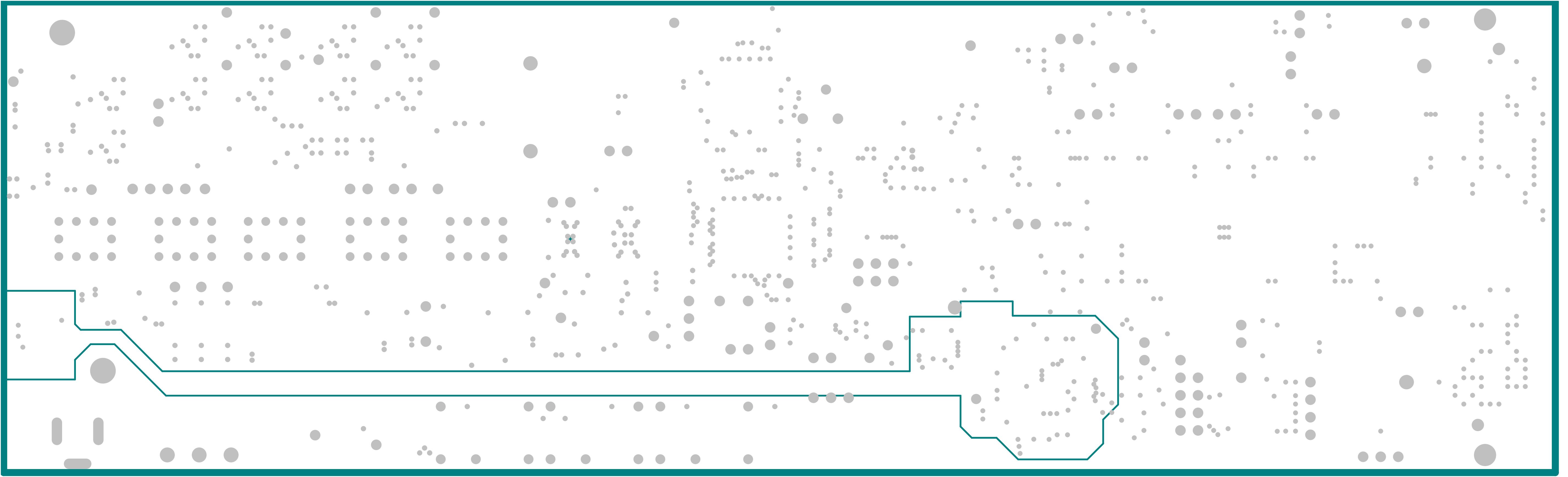
BOARD #: 6593635

REV: B

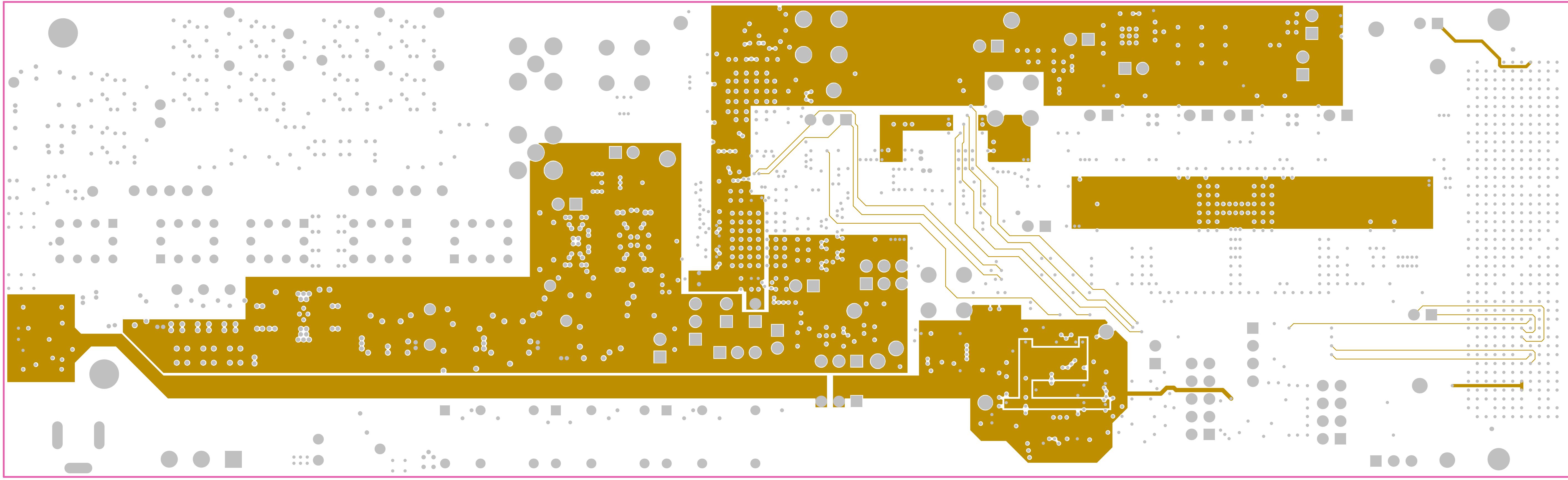
SUN REV: Not In VersionControl

DIRECTIONS

→



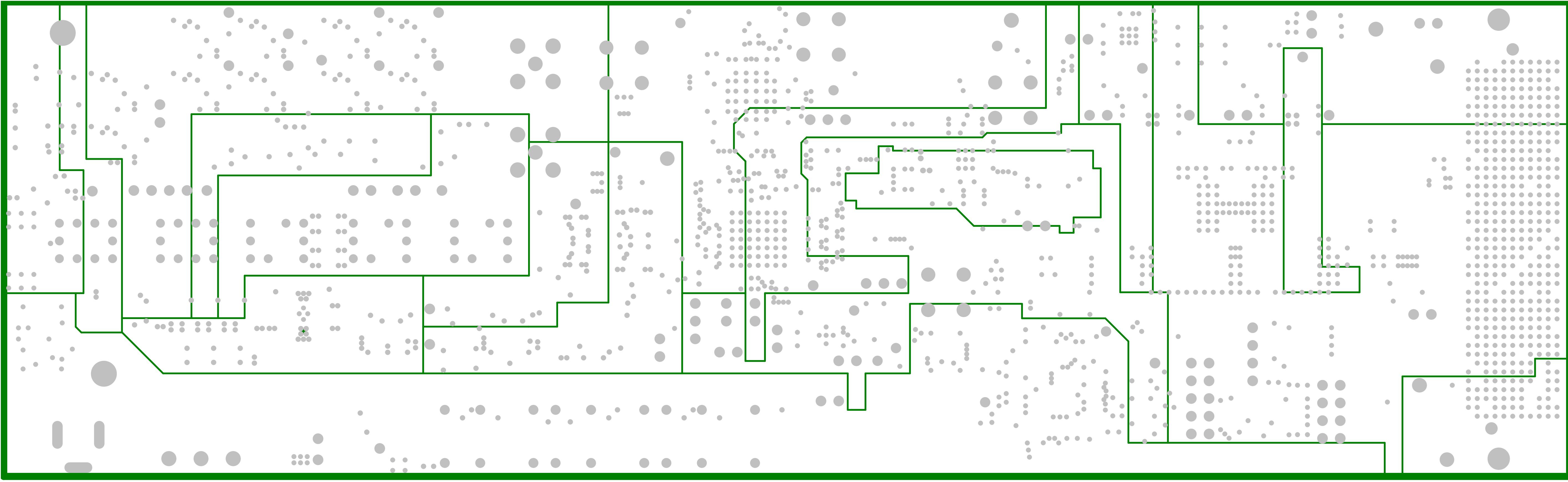
Gnd-Plane - L2



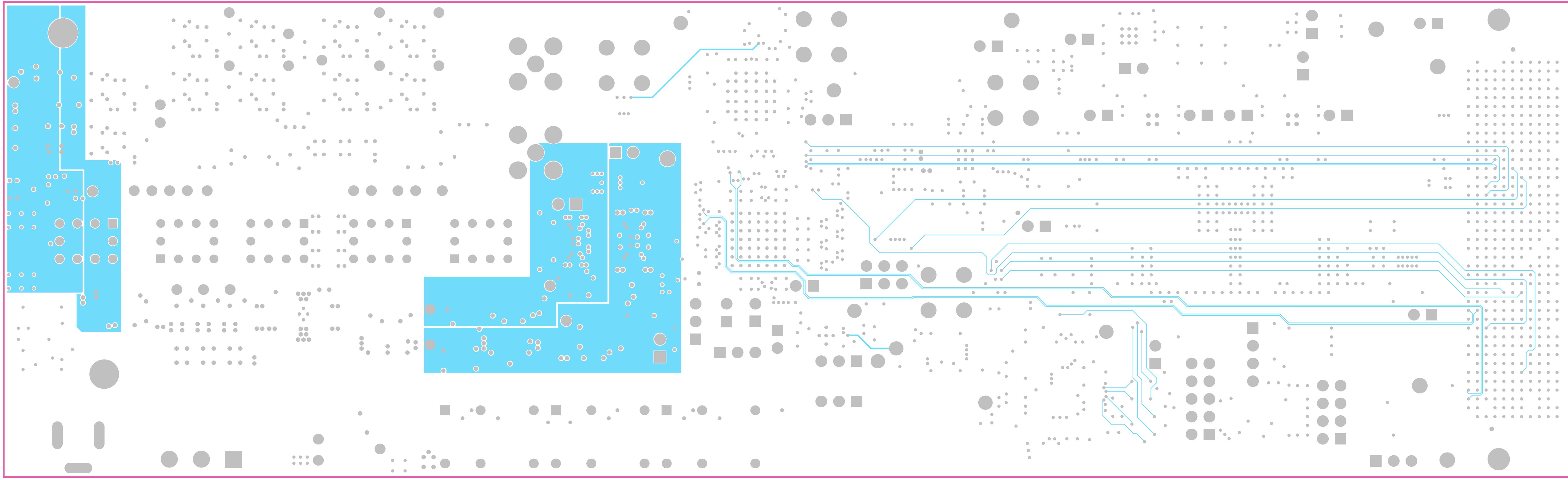
Signals - L3



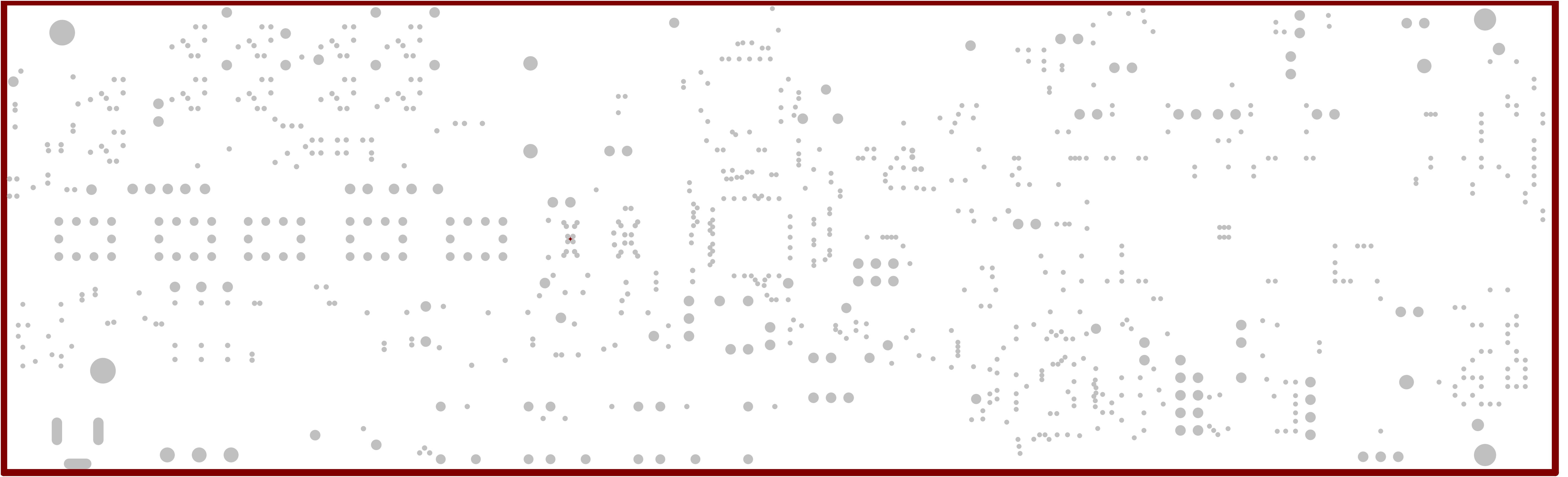
Gnd-Plane - L4



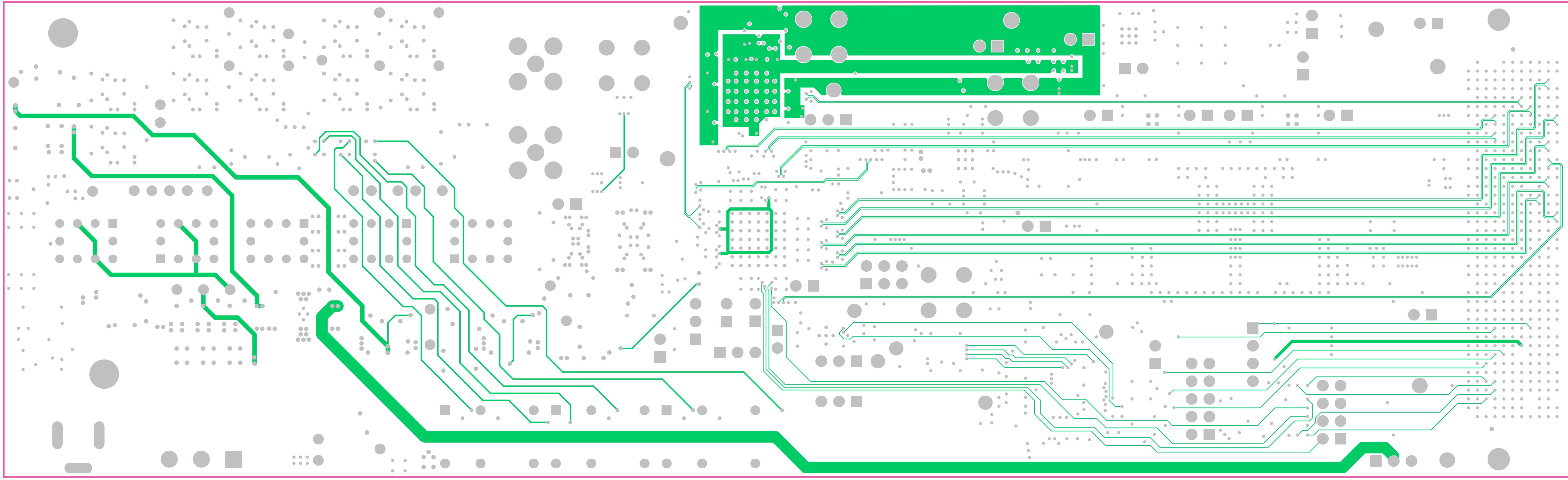
Pwr Plane - L5



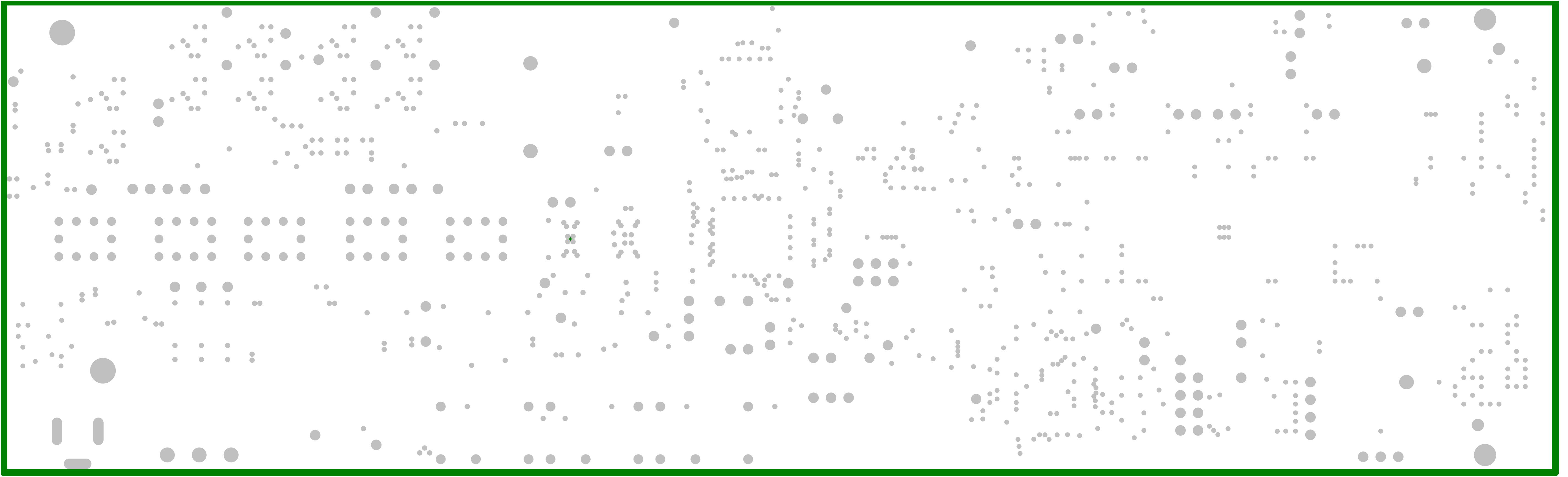
Signals - L6



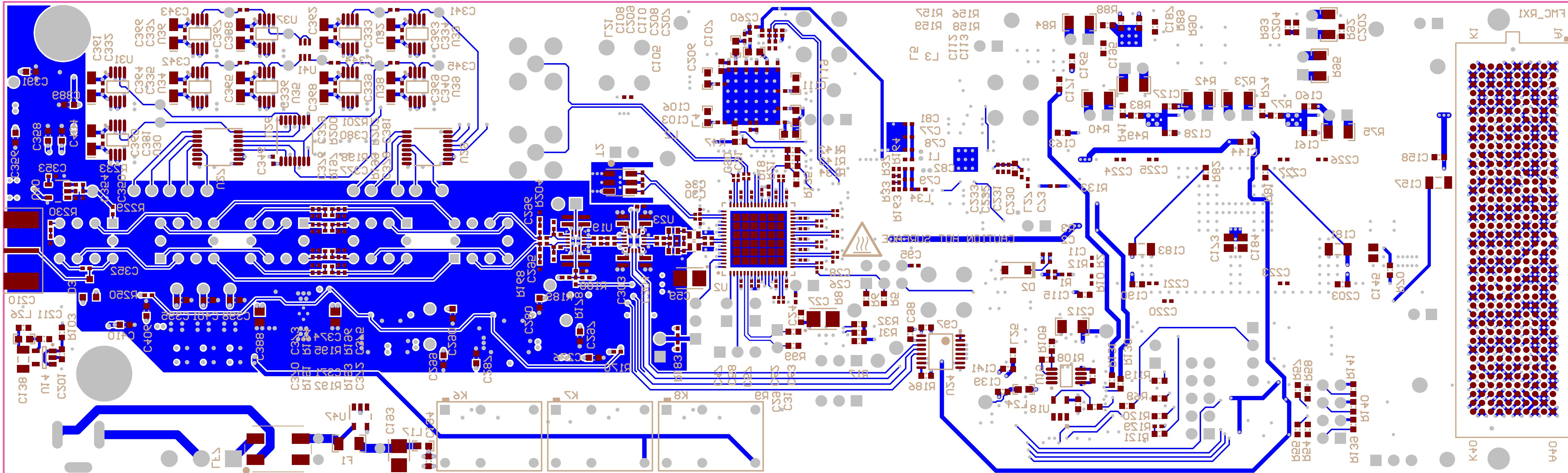
Gnd-Plane - L7

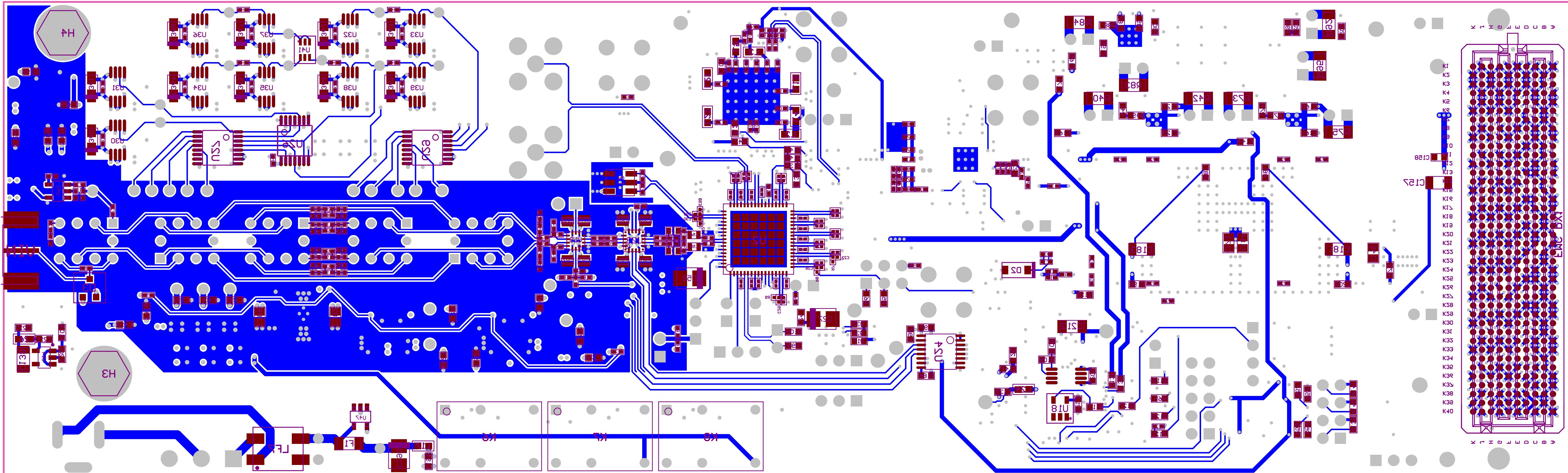


Signals - L8



Gnd-Plane - L9





PCB VIEWED FROM BOTTOM SIDE
BOARD #: 653635
REV: B
SUN REV: Not In Use/Out of Service
ASSEMBLY VARIANT: [No Variations]
COMPONENTS MARKED (DNP) SHOULD NOT BE POPULATED AND MAY NOT BE IN BILL OF MATERIALS

Bottom Layer - L10	IGNORE ->	PCB VIEWED FROM BOTTOM SIDE BOARD #: 653635 REV: B SUN REV: Not In Use/Out of Service ASSEMBLY VARIANT: [No Variations] COMPONENTS MARKED (DNP) SHOULD NOT BE POPULATED AND MAY NOT BE IN BILL OF MATERIALS
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